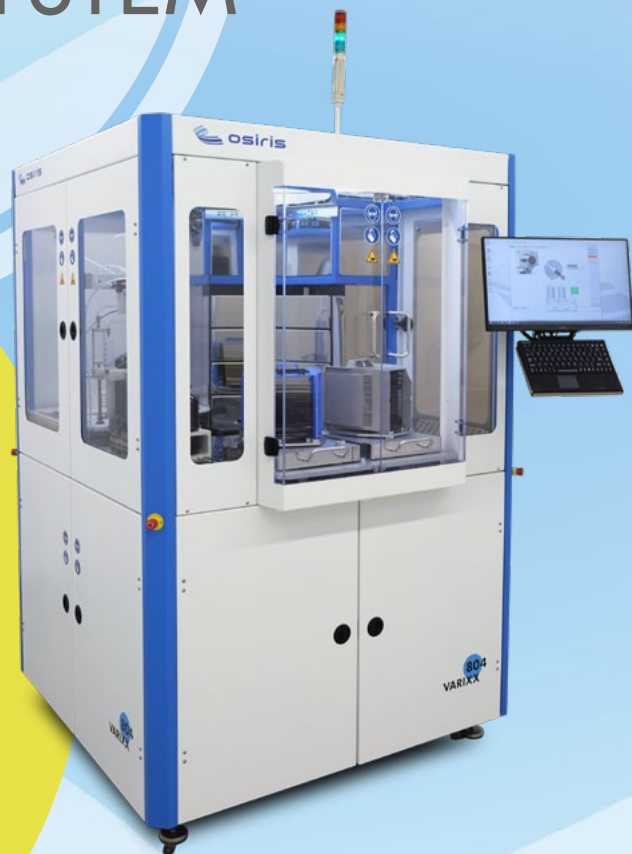


VARIXX 804

AUTOMATIC COMBINABLE CLUSTER SYSTEM

BENEFITS

- ÷ Substrate sizes up to 200mm (round) or 6"x 6" (square)
- ÷ Flexible configuration of process modules
- ÷ Dual arm robotic system for increasing throughput
- ÷ On-the-fly product alignment
- ÷ Full edge handling (backside protected) or standard vacuum gripping
- ÷ Handling for thin, standard or bonded wafer (Si, glass & others)
- ÷ SECS/GEM interface
- ÷ Standard and customized chuck design

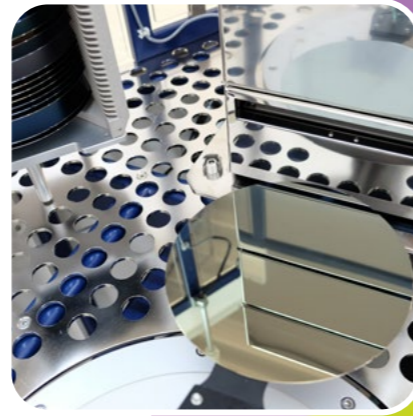


VARIXX 804
with 4 process modules

PROPERTIES

- ÷ Wafer size Ø2"/50mm up to Ø8"/200mm or square substrates up to 6" x 6" / 150 x 150mm
- ÷ Up to 4 selectable process modules:
 - Spin coater (CCP* or open bowl)
 - Spray coater (air brush or megasonic)
 - Developer (solvent or aqueous)
 - Temperature module tower (plug-and-play):
 - 1 basic stacks with 4 slots (max .5) for hot- & cool-plates or HMDS vapor prime hotplates or for a relax station.
 - Heating temperature for hotplates up to 300°C (optional up to 600°C)
 - EBR module (EBR on square substrate / on flat wafer or on wafer with notches)
- ÷ Wafer flipper
- ÷ IO stations (as option up to 4 stations)
- ÷ On-the-fly product alignment
- ÷ PR dispense system for low and high viscosity median utilizing the OSIRIS OYSTER PUMP (OOPXX)
- ÷ Full edge handling (backside protected) or standard vacuum gripping
- ÷ Central positioned handling system with single or dual robotic arm
- ÷ Configurable interfaces to external exposure system
- ÷ System control unit used for operation GUI (windows 7 or 10)
- ÷ SECS/GEM interface
- ÷ Steel frame powder coated
- ÷ Cleanroom class 10 (ISO 4)
- ÷ Optional upgrade of the FFU / Microclimate
- ÷ External media cabinets

* Covered Chuck Processor (CCP)



CONFIGURABLE FOR ROUND AND SQUARE SUBSTRATES

VARIXX 804 AUTOMATIC COMBINABLE CLUSTER SYSTEM

The system platform offers the customer the possibility to configure the system so that it can be optimally equipped for the required process.

This VARIXX 804 automatic cluster system can be equipped with spin or spray coat and developer process modules, HMDS (vapor primer), hotplates and cool-plates for wafer sizes Ø2"/50mm up to Ø8"/200mm or square substrates up to 6" x 6" / 150 x 150 mm.

One precise and fast running robotic, fixed in the center of the cluster are able to handle very thin fragile substrates very gently.

A system control unit via a 22" touchscreen display is used for optimum control and monitoring of the machine.

TECHNICAL DATA / VARIXX 804

REQUIREMENTS

Power:	400(208) VAC / 3 Phase / N / PE / 50(60) Hz
CDA:	8 ± 2 bar, tube OD Ø10 mm
Vacuum:	-0,8 bar / 24 in Hg, tube OD Ø10 mm
Nitrogen (optional):	4 - 6 bar, PE tube, OD Ø8 mm
DI-Water (optional):	3.0 + 1.0 bar
Exhaust process:	2x OD Ø110 mm, ca. 50 - 180 m ³ /h *
Exhaust hotpl. stack:	2x OD Ø110 mm, ca. 50 - 180 m ³ /h *
Exhaust cabinet:	3x OD Ø110 mm, ca. 50 - 250 m ³ /h *
Drain:	Waste canister with high-level sensor or facility drain connection or system to the facility*

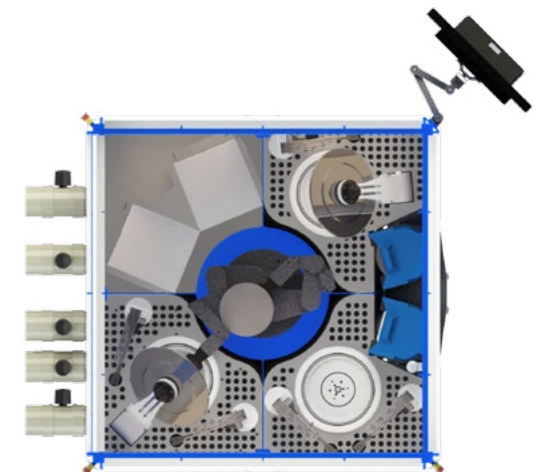
* chemical and process related

DIMENSIONS (WxDxH)

Frame (approx.):	1.300 x 1.300 x 2.100 mm (51.2" x 51.2" x 82.7")
Media cabinet:	Depending on configuration

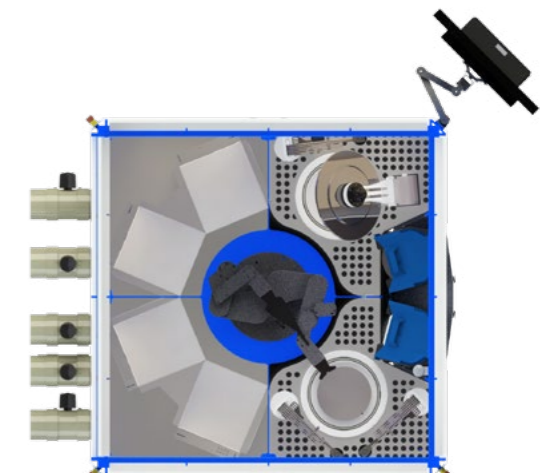
EXAMPLE CONFIGURATION 1

- ÷ 2x IO stations for carrier 200mm wafers
- ÷ 2x Spin coater module (CCP)
- ÷ 1x Spin coater module (open bowl)
- ÷ 2x Temperature module tower
 - With 8 (4 each) stacked slots:
 - 1x HMDS Hotplate
 - 4x Hotplates
 - 2x Cool-plates
 - 1x Relax stations
- ÷ Central robotic systems with 2-arms
- ÷ Control unit with 22" touch display



EXAMPLE CONFIGURATION 2

- ÷ 2x IO stations for carrier 200mm wafers
- ÷ 1x Spin coater module (CCP)
- ÷ 1x Developer
- ÷ 4x Temperature module tower
 - With 16 (4 each) stacked slot:
 - 2x HMDS plates
 - 8x Hotplates
 - 4x Cool-plates
 - 2x Relax stations
- ÷ Central robotic systems with 2-arms
- ÷ Control unit with 22" touch display





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Version: VARIXX-804 Osiris system 200630

Data, design and specification of custom built machines depend on individual process conditions and can vary according to equipment configurations. Not all specifications may be valid simultaneously. Illustrations in this brochure are not legally binding. Osiris International GmbH reserves the right to change machine specifications without prior notice.